**Product data sheet** 

## 1. General description

Planar passivated high commutation three quadrant triac in a SOT54 (TO-92) plastic package. This "series DN" triac balances the requirements of commutation performance and gate sensitivity and is intended for interfacing with low power drivers and logic ICs including microcontrollers.

## 2. Features and benefits

- 3Q technology for improved noise immunity
- Direct gate triggering from low power drivers and logic ICs
- · High commutation capability with very sensitive gate
- · High voltage capability
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only
- · Very sensitive gate for easy logic level triggering

# 3. Applications

- Low power motor controls
- · Small inductive loads e.g. solenoids, door locks, water valves
- · Small loads in large white goods

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit
Absolute	maximum rating			
$V_{DRM}$	repetitive peak off-state voltage		1000	V
I <sub>T(RMS)</sub>	RMS on-state current	square-wave pulse; T <sub>lead</sub> ≤ 57 °C; Fig. 1; Fig. 2; Fig. 3	0.8	А
I <sub>TSM</sub>	non-repetitive peak forward current	full sine wave; $t_p$ = 20 ms; $T_{j(init)}$ = 25 °C; Fig. 4; Fig. 5	9	А
		full sine wave; $t_p$ = 16.7 ms; $T_{j(init)}$ = 25 °C	9.9	Α
T <sub>j</sub>	junction temperature		125	°C

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	aracteristics					
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G + T_j = 25 \text{ °C; } Fig. 7$	0.25	-	5	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G T_j = 25 \text{ °C; } Fig. 7$	0.25	-	5	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2-\text{ G-} $ $T_j = 25 \text{ °C; } Fig. 7$	0.25	-	5	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	-	10	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 0.85 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.3	1.6	V
Dynamic	characteristics		'			
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 670 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit	-	150	-	V/µs
dI <sub>com</sub> /dt	rate of change of commutating current	$V_D = 400 \text{ V}; T_j = 125 \text{ °C}; I_{T(RMS)} = 0.8 \text{ A};$ $dV_{com}/dt = 10 \text{ V/}\mu\text{s}; gate open circuit;}$	0.5	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 125 \text{ °C}; I_{T(RMS)} = 0.8 \text{ A};$ $dV_{com}/dt = 1 \text{ V}/\mu\text{s}; gate open circuit}$	1	-	-	A/ms

# 5. Pinning information

**Table 2. Pinning information** 

10010 211	mining initori			
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T2	main terminal 2		T2—T1
2	G	gate	ļ <b></b>	G sym051
3	T1	main terminal 1	(1000	symoon

# 6. Ordering information

**Table 3. Ordering information** 

· · · · · · · · · · · · · · · · · · ·						
Type number	Package	ckage				
	Name	Description	Version			
BTA2008-1000DN	TO-92	plastic single-ended leaded (through hole) package; 3 leads	SOT54			

# 7. Marking

**Table 4. Marking codes** 

Type number	Marking codes
BTA2008-1000DN	BTA2008-1000DN

BTA2008-1000DN

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# 8. Limiting values

#### **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{DRM}$	repetitive peak off-state voltage		1000	V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; $T_{lead} \le 57^{\circ}C$ ; <u>Fig. 1</u> ; <u>Fig. 2</u> ; <u>Fig. 3</u>	0.8	А
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; $t_p$ = 20 ms; $T_{j(init)}$ = 25 °C; Fig. 4; Fig. 5	9	А
		full sine wave; $t_p$ = 16.7 ms; $T_{j(init)}$ = 25 °C	9.9	А
l <sup>2</sup> t	I <sup>2</sup> t for fusing	t <sub>p</sub> = 10ms; sine wave	0.41	A²/s
dl <sub>⊤</sub> /dt	rate of rise of on-state current	I <sub>G</sub> = 10mA	100	A/µs
I <sub>GM</sub>	peak gate current		1	А
$P_{GM}$	peak gate power		2	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.1	W
T <sub>stg</sub>	storage temperature		-40 to 150	°C
T <sub>j</sub>	junction temperature		125	°C

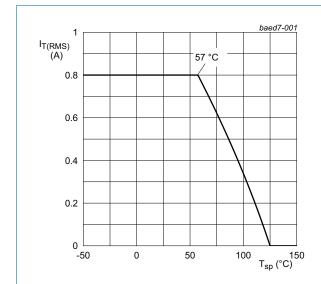
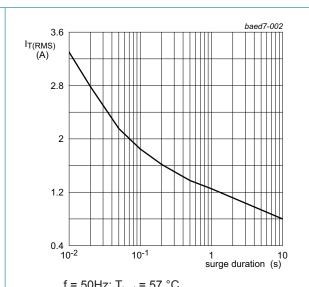


Fig. 1. RMS on-state current as a function of solder point temperature; maximum values



f = 50Hz;  $T_{lead}$  = 57 °C Fig. 2. RMS on-state current as a function of surge duration; maximum values

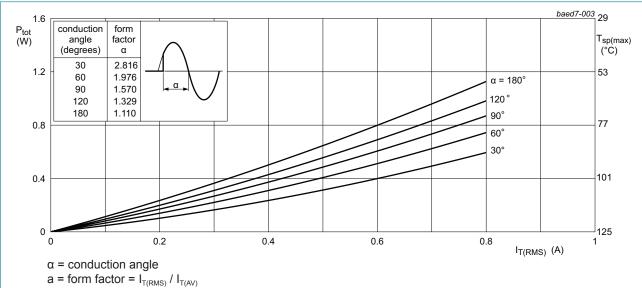


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

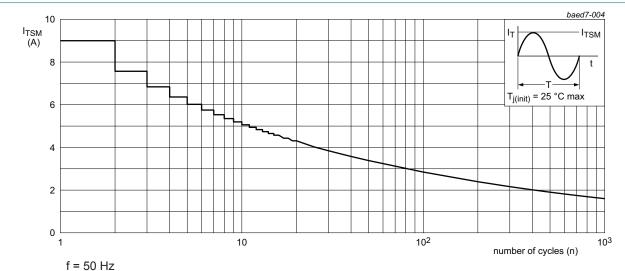


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

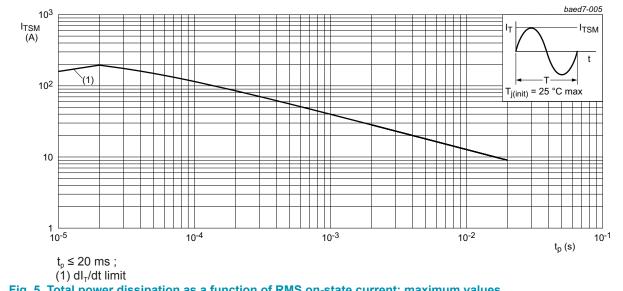


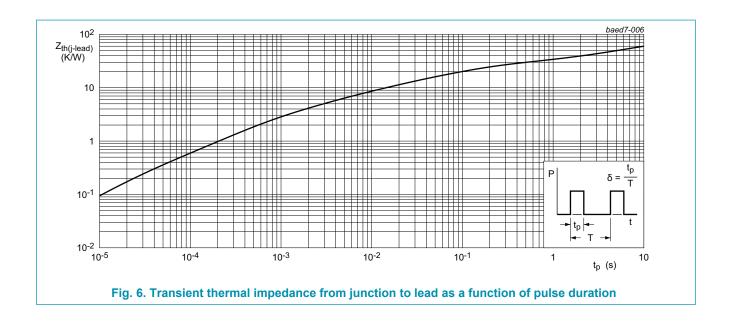
Fig. 5. Total power dissipation as a function of RMS on-state current; maximum values

3Q Triad

## 9. Thermal characteristics

#### Table 5. Thermal characteristics

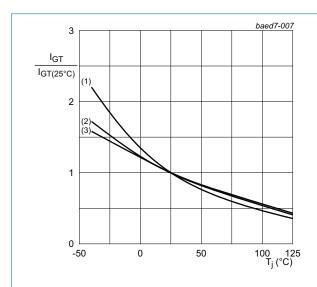
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{\text{th(j-lead)}}$	thermal resistance from junction to lead	Fig. 6	-	-	60	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	150	-	K/W



## 10. Characteristics

## **Table 7. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					'
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + \text{ G+;}$ $T_j = 25 \text{ °C; } \underline{\text{Fig. 7}}$	0.25	-	5	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + \text{ G-;}$ $T_j = 25 \text{ °C; } \underline{\text{Fig. 7}}$	0.25	-	5	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2-\text{ G-;}$ $T_j = 25 \text{ °C; } \underline{\text{Fig. 7}}$	0.25	-	5	mA
l <sub>L</sub>	latching current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2+ \text{ G+;} $ $T_j = 25 \text{ °C; } \underline{\text{Fig. 8}}$	-	-	10	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-;$ $T_j = 25 \text{ °C; } Fig. 8$	-	-	20	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-;}$ $T_j = 25 \text{ °C; } Fig. 8$	-	-	10	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	-	10	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 0.85 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.3	1.6	V
$V_{GT}$	gate trigger voltage	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T_j = 25 \text{ °C;}$ Fig. 11	-	0.85	1	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 125 \text{ °C};$ Fig. 11	0.2	0.3	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 1000 V; T <sub>j</sub> = 25 °C	-	-	10	μA
		V <sub>D</sub> = 1000 V; T <sub>j</sub> = 125 °C	-	0.1	0.5	mA
Oynamic o	characteristics					
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 670 V; $T_{j}$ = 125 °C; $(V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit	-	150	-	V/µs
dI <sub>com</sub> /dt	rate of change of commutating current	$V_D = 400 \text{ V; } T_j = 125 \text{ °C; } I_{T(RMS)} = 0.85 \text{ A;} $ $dV_{com}/dt = 10 \text{ V/}\mu\text{s; gate open circuit}$	0.5	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 125 \text{ °C}; I_{T(RMS)} = 0.85 \text{ A};$ $dV_{com}/dt = 1 \text{ V/}\mu\text{s}; gate open circuit}$	1	-	-	A/ms



- (1) T2- G-
- (2) T2+ G-
- (3) T2+ G+

Fig. 7. Normalized gate trigger current as a function of junction temperature

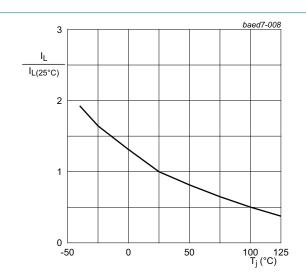


Fig. 8. Normalized latching current as a function of junction temperature

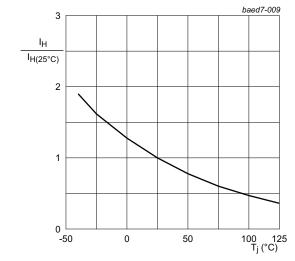
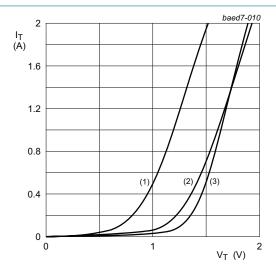


Fig. 9. Normalized holding current as a function of junction temperature

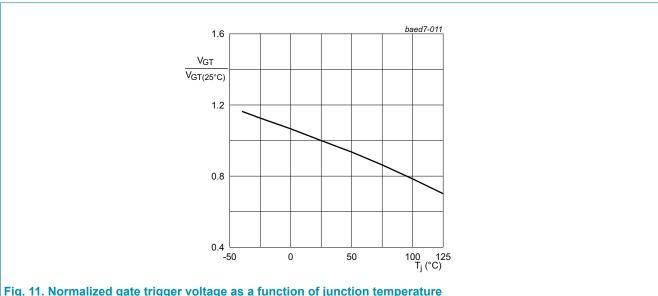


 $V_o = 1.220 \text{ V}; R_s = 0.3875 \Omega$ 

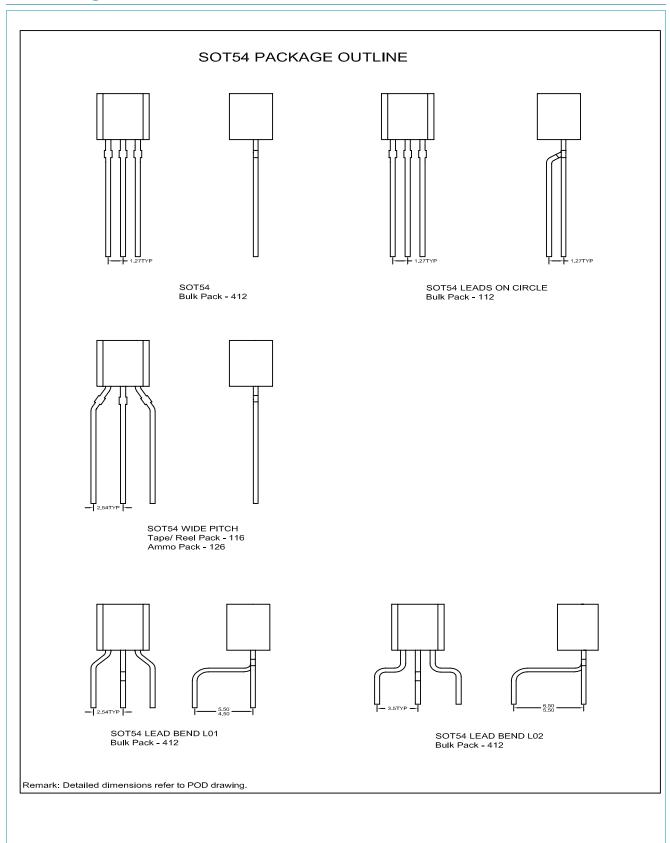
(1)  $T_j = 125$  °C; typical values (2)  $T_j = 125$  °C; maximum values

(3)  $T_i = 25$  °C; maximum values

Fig. 10. On-state current as a function of on-state voltage



# 11. Package outline



3Q Triad

## 12. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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